L Number	Hits	Search Text	DB	Time stamp
1	483	257/798	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/26 21:45
2	2447	wafer with (recess or open$3 or cavity or aperture or hole) with align$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/26 21:47
3	1465	wafer with (recess or open$3 or cavity or aperture or hole) with align$4	USPAT	2004/10/26 22:15
4	0	(wafer with (recess or open$3 or cavity or aperture or hole) with align$4) not (wafer with (recess or open$3 or cavity or aperture or hole) with align$4)	USPAT	2004/10/26 22:16
5	982	(wafer with (recess or open$3 or cavity or aperture or hole) with align$4) not (wafer with (recess or open$3 or cavity or aperture or hole) with align$4)	US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/26 22:32
6	742	438/401	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/26 22:34
7	947	438/462	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/26 22:40
8	1466	438/975	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/26 22:48
9	1703	430/394	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/26 22:50
-	1079	257/797	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/26 21:30